



元耀科技股份有限公司

YENYO TECHNOLOGY CO., LTD.

BT08 Series

8A TRIACs

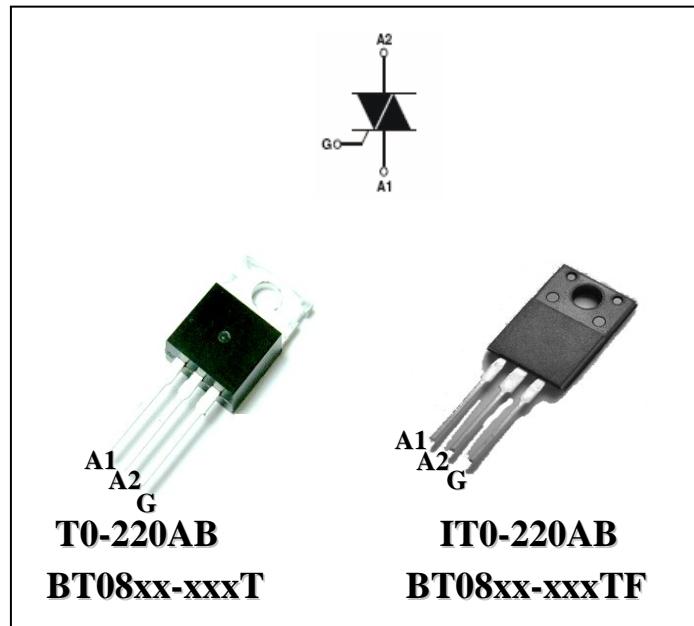
4-Quardrant Triacs (standard & logic level)

Main features

Symbol	Value	Unit
$I_{T(RMS)}$	8	A
V_{DRM}/V_{RRM}	600	V
$I_{GT(Q1)}$	10 to 35	mA

DESCRIPTION

The BT08 series is suitable for use on AC inductive loads. These devices intended to be interface directly to micro-controllers, logic integrated circuits and other low power gate trigger circuits....



Absolute maximum ratings

Symbol	Parameter			Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave) , $T_{mb} \leq 102^\circ\text{C}$			8	A
I_{TSM}	Non repetitive surge on-state current (full sine wave , T_j initial=25°C)	$F = 50\text{Hz}$	$t = 20\text{ms}$	65	A
		$F = 60\text{Hz}$	$t = 16.7\text{ms}$	72	
I^2t	I^2t Value for fusing	$t_p = 10\text{ms}$		21	A^2s
dl/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $tr \leq 100\text{ns}$	$F = 120\text{Hz}$	$T_j = 125^\circ\text{C}$	50	$\text{A}/\mu\text{s}$
I_{GM}	Peak gate current	$t_p = 20\mu\text{s}$	$T_j = 125^\circ\text{C}$	2	A
$P_{G(AV)}$	Average gate power dissipation		$T_j = 125^\circ\text{C}$	0.5	W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			-40 to +150 -40 to +125	°C

Electrical characteristics ($T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test conditions	Quadrant	BT08			Unit	
			10	25	35		
$I_{GT}(1)$	$V_D = 12\text{V}$ $RL=100 \text{ ohm}$	I - II - III	MAX.	10	25	35	mA
V_{GT}		IV		25	50	70	
$I_H(2)$	$I_T = 100 \text{ mA}$		MAX.	1.5		V	
I_L	$I_G = 1.2 I_{GT}$	I - III	MAX.	25	35	50	mA
		II-IV		35	45	60	

Static characteristics

Symbol	Test conditions			Value	Unit
$V_T(2)$	$I_{TM} = 10\text{A}$	$tp = 380 \text{ us}$	$T_j = 25^\circ\text{C}$	MAX.	1.65 V
I_{DRM} I_{RRM}	$V_{DRM}=V_{RRM}$		$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	MAX.	5 uA 1 mA

Note 1 : minimum I_{GT} is guaranteed at 5% of I_{GT} max.

Note 2 : for both polarities of A2 referenced to A1

Thermal resistance

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-mb)}$	Junction to mounting base	Full cycle Half cycle	2.0(max.) 2.4(max.)	K/W
$R_{th(j-a)}$	Junction to ambient	In free air	60(typ.)	K/W



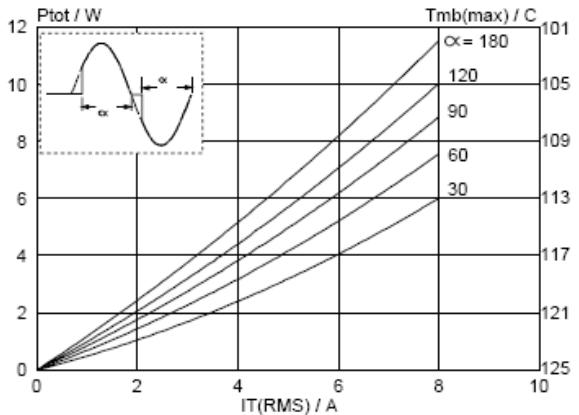


Fig. 1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $IT_{(RMS)}$, where α = conduction angle.

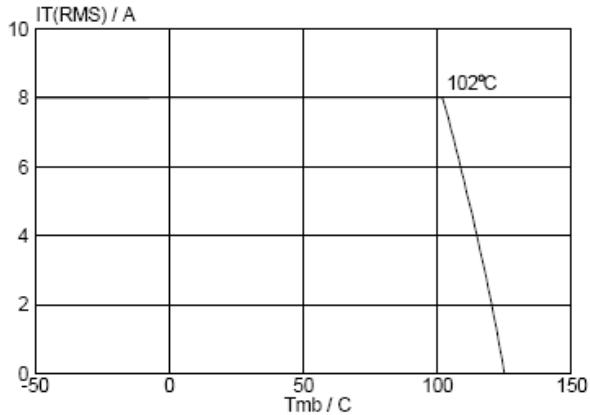


Fig. 4. Maximum permissible rms current $IT_{(RMS)}$, versus mounting base temperature T_{mb} .

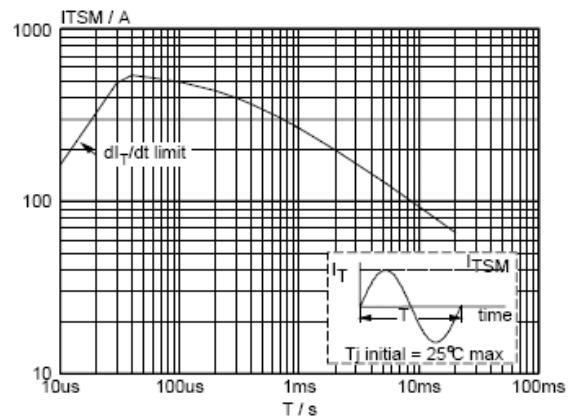


Fig. 2. Maximum permissible non-repetitive peak on-state current IT_{SM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20\text{ms}$.

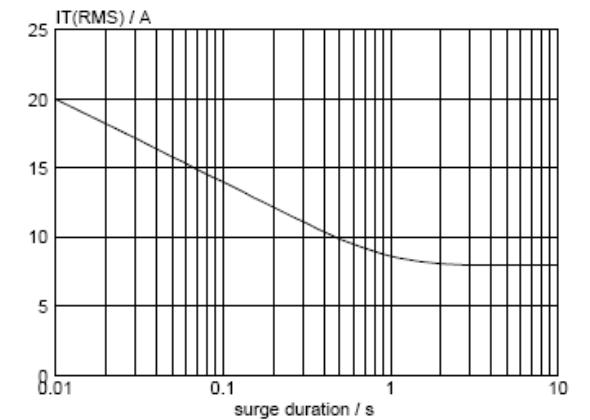


Fig. 5. Maximum permissible repetitive rms on-state current $IT_{(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50\text{ Hz}$; $T_{mb} \leq 102^\circ\text{C}$.

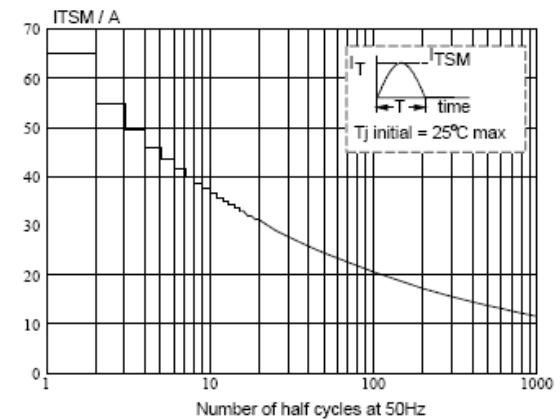


Fig. 3. Maximum permissible non-repetitive peak on-state current IT_{SM} , versus number of cycles, for sinusoidal currents, $f = 50\text{ Hz}$.

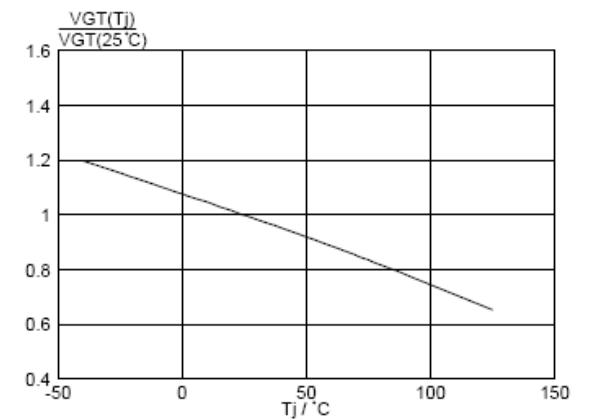


Fig. 6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$, versus junction temperature T_j .



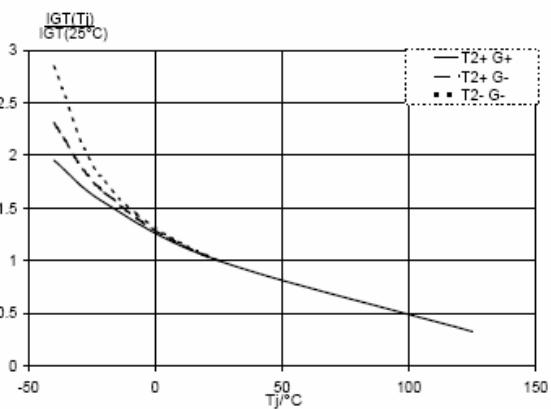


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

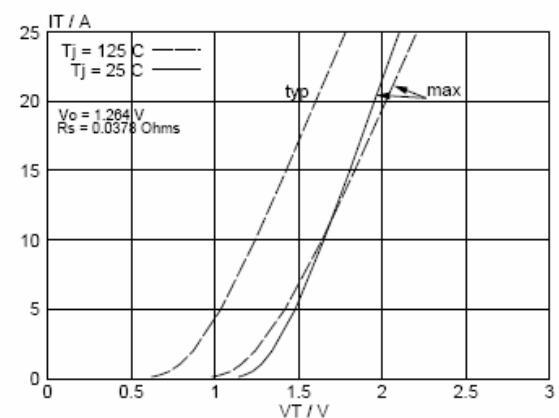


Fig.10. Typical and maximum on-state characteristic.

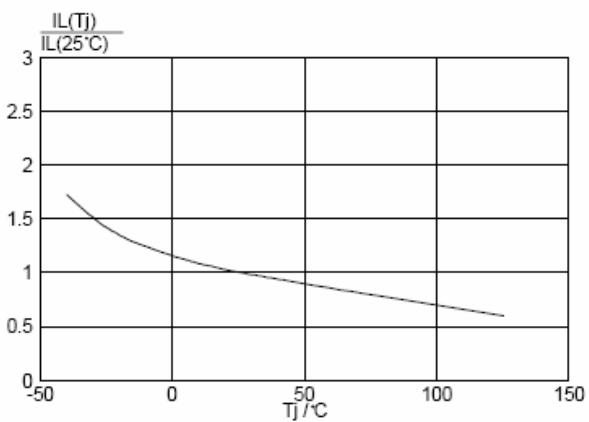


Fig.8. Normalised latching current $I_L(T_j)/I_L(25^\circ\text{C})$, versus junction temperature T_j .

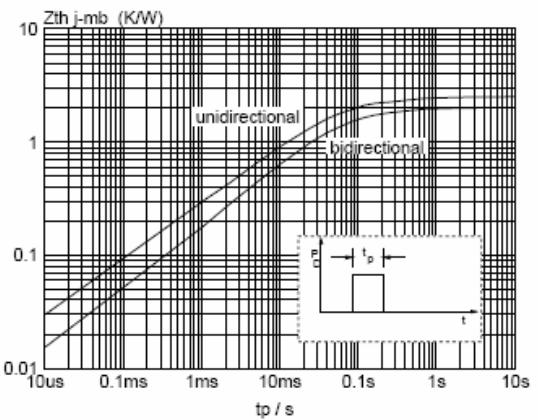


Fig.11. Transient thermal impedance $Z_{th,j-mb}$, versus pulse width t_p .

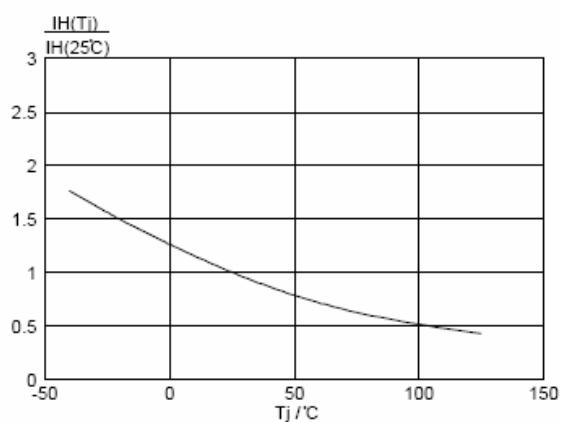


Fig.9. Normalised holding current $I_H(T_j)/I_H(25^\circ\text{C})$, versus junction temperature T_j .



Product selector

Part Number	Voltage (xxx)	Sensitivty	Package
	600V		
BT0810-XXXT	X	10mA	TO-220AB
BT0810-XXXTF	X	10mA	ITO-220AB
BT0825-XXXT	X	25mA	TO-220AB
BT0825-XXXTF	X	25mA	ITO-220AB
BT0835-XXXT	X	35mA	TO-220AB
BT0835-XXXTF	X	35mA	ITO-220AB

